EMI Ferrite Bead



BBUP Series



Overview

EMI ferrite beads are made of ferrite material, which can block high-frequency noise while allowing required signals to pass through, providing high impedance and noise attenuation to improve signal integrity/efficiency and reduce power loss.

Benefits

- 1. For Power Line
- 2. Compliance with EMI regulations.
- 3. Reduced power loss and improved system efficiency
- 4. Operating temperature range: -55 ~ +125°C
- 5. Improved signal integrity

Applications

- 1. Wearable device
- 2. Industrial
- 3. Communications
- 4. Consumer Electronics

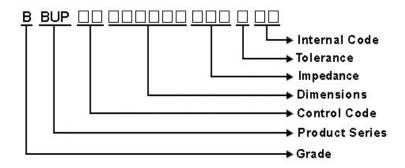
Product Information

| Series | Size Code (JIS/EIA) | Impedance (Ω) |
|--------|---------------------|---------------|
| BBUP | 1005/0402 | 10 ~ 470 |
| | 1608/0603 | |
| | 2012/0805 | |
| | 3216/1206 | |
| | 4532/1812 | |





- 1 Scope: This specification applies to MULTILAYER FERRITE CHIP BEADS
- 2 Part Numbering:



3 Rating:

Operating Temperature: -55°C ~ 125 °C(Including self - temperature rise)

Storage Temperature: - 5 5 °C ~ 1 2 5 °C(after PCB)

- $5 ^{\circ}\text{C} \sim 4 \ 0 ^{\circ}\text{C}$, Humidity $4 \ 0 \% \sim 7 \ 0 \%$ (before PCB)

4 Marking:

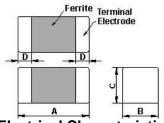
No Marking

5 Standard Testing Condition

| | Unless otherwise specified | |
|-------------|---------------------------------|--------------|
| Temperature | Ordinary Temperature(15 to 35℃) | 20 to 30°C |
| Humidity | Ordinary Humidity(25 to 85% RH) | 50 to 80 %RH |



6 Configuration and Dimensions:



| Dimensions in mm | | | | |
|------------------|----------|--|--|--|
| TYPE | 160808 | | | |
| Α | 1.6±0.15 | | | |
| В | 0.8±0.15 | | | |
| С | 0.8±0.15 | | | |
| D | 0.3±0.20 | | | |

| Net Weight (grms) | |
|-------------------|-------------------|
| Size Code | Net Weight (grms) |
| 160808 | 0.00576 |

7 Electrical Characteristics:

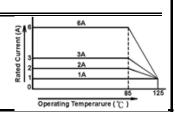
| Part No. | Impedance | Test Freq. | RDC | Rated Current |
|--------------------|-----------|----------------|---------|------------------|
| | (Ω) | • | (Ω)Max. | (mA)Max. |
| BBUP00160808100□00 | 10 | 100 MHz,200 mV | 0.01 | 5000 |
| BBUP00160808300□00 | 30 | 100 MHz,200 mV | 0.015 | 4500 |
| BBUP00160808600□00 | 60 | 100 MHz,200 mV | 0.02 | 4000 |
| BBUP00160808700□00 | 70 | 100 MHz,200 mV | 0.02 | 4000 |
| BBUP00160808101□00 | 100 | 100 MHz,200 mV | 0.03 | 3000 |
| BBUP00160808121□00 | 120 | 100 MHz,200 mV | 0.03 | 3000 |
| BBUP00160808181□00 | 180 | 100 MHz,200 mV | 0.05 | 2000 |
| BBUP00160808221□00 | 220 | 100 MHz,200 mV | 0.04 | 2500 |

NOTE: □-tolerance Y=±25% / T=±30%

1. Operating temperature range - 5 5 $^{\circ}$ C ~ 1 2 5 $^{\circ}$ C(Including self - temperature rise)

2.Rate Current : Applied the current to coils, the temperature rise shall not be more than 30°C

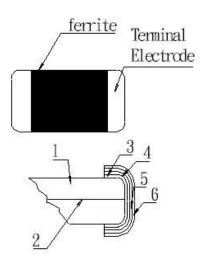
3.As for BBUP type. Rated Current is derated as right figure depending on the operating temprature.





8 BBUP00160808 Series

8.1 Construction:



8.2 Material List:

| No | Part | Material |
|----|-------------------|---------------------|
| 1 | Ferrite Substance | NiO-CuO-ZnO-Ferrite |
| 2 | Silver electrode | Ag |
| 3 | Silver electrode | Ag |
| 4 | Cu plating | Cu |
| 5 | Ni plating | Ni |
| 6 | Sn plating | Sn |

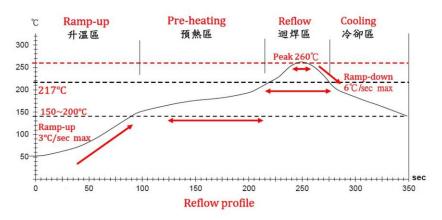


9 Reliability Of Ferrite Multilayer Chip Bead 1-1.Mechanical Performance

| No | Item | Specification | Test Method | | |
|-------|------------------------------|---------------------------------|---|--|--|
| 1-1-1 | Flexure Strength | The forces applied on the right | Test device shall be soldered on the substrate | | |
| | | conditions must not damage | Substrate Dimension: 100x40x1.6mm | | |
| | | the terminal electrode and the | Deflection: 2.0mm | | |
| | | ferrite | Keeping Time: 30sec | | |
| | | | *For 100505, substrate dimension is 100x40x0.8mm | | |
| 1-1-2 | Vibration | | Test device shall be soldered on the substrate | | |
| | | | Oscillation Frequency: 10 to 55 to 10Hz for 1min | | |
| | | | Amplitude: 1.5mm | | |
| | | | Time: 2hrs for each axis (X, Y & Z), total 6hrs | | |
| 1-1-3 | Resistance to Soldering Heat | Appearance: No damage | Pre-heating: 150°ℂ, 1min | | |
| | | More than 75% of the termina | Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) | | |
| | | electrode should be covered | Solder Temperature: 260±5°C | | |
| | | with solder. | Immersion Time: 10±1sec | | |
| | | Impedance: within ±30% of | | | |
| | | initial value | | | |
| 1-1-4 | Solder ability | The electrodes shall be at | Pre-heating: 150°C, 1min | | |
| | | least 95% covered with new | Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) | | |
| | | solder coating | Solder Temperature: 245±5°C (Pb-Free) | | |
| | | | Immersion Time: 4±1sec | | |
| | | | | | |
| 1-1-5 | Terminal Strength Test | No split termination | Test device shall be soldered on the substrate, | | |
| | | Chip | then apply a force in the direction of the arrow. | | |
| | | F F | Force: 5N | | |
| | | | Keeping Time: 10±1sec | | |
| | | | | | |
| | | Mounting Pad | | | |

| No | Item | Specification | | • | | |
|-------|------------------------|--------------------------|--|---------------------------------------|-------------------|--|
| 1-2-1 | Temperature Cycle | Appearance: No damage | One cycle: | | | |
| | | Impedance: within±30% of | Step | Temperature (°C) | Time (min) | |
| | | initial value | 1 | -55±3 | 30 | |
| | | | 2 | 25±2 | 3 | |
| | | | 3 | 125±3 | 30 | |
| | | | 4 | 25±2 | 3 | |
| | | | Total: 100d | cycles | | |
| | | | Measured | after exposure in the room co | ndition for 24hrs | |
| 1-2-2 | Humidity Resistance | | Temperature: 40±2°C | | | |
| | | | Relative Humidity: 90 ~ 95% / Time: 1000hrs | | | |
| | | | Measured after exposure in the room condition for 24hrs | | | |
| 1-2-3 | High | | Temperatu | ıre: 125±3°€ / Relative Humid | ity: 0% | |
| | Temperature Resistance | | Applied Cu | ırrent: Rated Current /Time: 1 | 000hrs | |
| | | | Measured after exposure in the room condition for 24hrs Temperature: -55±3°C | | | |
| 1-2-4 | Low | | | | | |
| | Temperature Resistance | | Relative H | Relative Humidity: 0% / Time: 1000hrs | | |
| | | | Moscurod | after exposure in the room co | ndition for 24hra | |





Lead-Free(LF)標準溫度分析範圍

Refer to J-STD-020C

| 管制項目 Item. | 升溫區 Ramp-up | 預熱區 Pre-heating | 迴焊區 Reflow | Peak Temp | 冷卻區 Cooling |
|---------------------|----------------|--------------------|---------------|-------------|-----------------|
| 溫度範圍 Temp.scope | R.T ~ 150°C | 150°C ~ 200°C | Above 217°C | 260±5°C | Peak Temp.~150℃ |
| 標準時間 Time spec. | - | 60 ~ 180 sec | 60 ~ 150 sec | 20 ~ 40 sec | - |
| 實際時間 Time result | - | 75 ~ 100 sec | 90 ~ 120 sec | 20 ~ 35 sec | - |

NOTE:

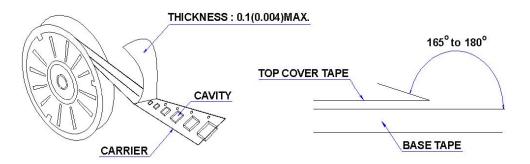
- 1. Re-flow possible times: within 2 times
- 2. Nitrogen adopted is recommended while in re-flow
- 3. Products can only be soldered with reflow



11 Packaging:

11.1 Packaging -Cover Tape

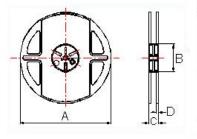
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

| TYPE | PCS/REEL | |
|--------|----------|--|
| 100505 | 10000 | |
| 160805 | 10000 | |
| 160808 | 4000 | |
| 201209 | 4000 | |

11.3 Reel Dimensions

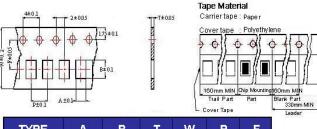


| TYPE | А | В | С | D |
|--------|-----|----|----|-----|
| 100505 | 178 | 60 | 12 | 1.5 |
| 160805 | 178 | 60 | 12 | 1.5 |
| 160808 | 178 | 60 | 12 | 1.5 |
| 201209 | 178 | 60 | 12 | 1.5 |



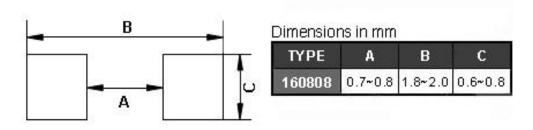
11 Packaging:

11.4 Tape Dimensions in mm



| TYPE | A | В | T | W | P | F |
|--------|------|------|------|---|---|-----|
| 100505 | 0.62 | 1.12 | 0.60 | 8 | 2 | 3.5 |
| 160805 | 1.05 | 1.85 | 0.60 | 8 | 2 | 3.5 |
| 160808 | 1.05 | 1.85 | 0.95 | 8 | 4 | 3.5 |
| 201209 | 1.50 | 2.30 | 0.97 | 8 | 4 | 3.5 |

12 Recommended Land Pattern:



13 Note:

- 1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)
- 5. The moisture sensitivity level (MSL) of products is classified as level 1.



